

IN THE CLAIMS-

Please amend the claims as follows:

1. (currently amended): An uncured pigmented layer that is intended to be attached directly to a face sheet of a panel, said panel comprising said face sheet for use as the top coat layer in a panel assembly that includes a core and at least one face sheet attached to said and a core, said face sheet including a composite layer that is formed by curing an uncured prepreg at a cure temperature for a sufficient time to form said face sheet ~~and wherein said uncured pigmented layer is attached to the uncured prepreg without an adhesive~~, said uncured pigmented layer comprising:

an uncured pigmented binder resin, said uncured pigmented binder resin comprising an uncured thermoplastic resin and a pigment wherein said uncured thermoplastic resin has a cure temperature that is equal to or less than the cure temperature of said uncured prepreg; and

a substrate on which said pigmented binder resin is located, said substrate having a melting point that is above the cure temperature of said prepreg and wherein said substrate comprises a textile substrate and/or a film substrate.

2. (currently amended): An uncured pigmented layer according to claim 1 wherein said substrate comprises ~~a textile substrate and/or~~ a thermoplastic film substrate.

3. (original): An uncured pigmented layer according to claim 1 wherein said uncured thermoplastic resin present in said uncured pigmented binder is polyvinyl butyral.

4. (currently amended): An uncured pigmented layer according to claim 1 wherein said uncured ~~thermosetting resin present in said prepreg is~~ comprises a thermosetting resin selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy.

5. (original): An uncured pigmented layer according to claim 4 wherein said uncured pigmented binder is polyvinyl butyral.

6. (original): An uncured pigmented layer according to claim 1 in which said substrate comprises a thermoplastic film substrate comprising polyethylene terephthalate.

7. (currently amended): An uncured pigmented layer according to claim ~~2~~ 1 wherein said textile substrate comprises a textile selected from the group consisting of glass fabric and polyester matt.

8. (original): An uncured pigmented layer according to claim 6 wherein said thermoplastic film substrate comprising polyethylene terephthalate is between about 36 and 50 microns thick.

9. (original): An uncured pigmented layer according to claim 1 wherein said pigment comprises titanium dioxide.

10. (original): An uncured pigmented layer according to claim 9 wherein said uncured thermoplastic resin present in said uncured pigmented binder comprises polyvinyl butyral, said uncured thermosetting resin present in said prepreg is selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy and said substrate comprises a thermoplastic film substrate comprising polyethylene terephthalate.

11. (currently amended): An uncured panel assembly comprising a:

a core having a first and a second surface, said first and second surfaces being located on opposite sides of said core and defining the thickness of said core;

at least one uncured prepreg located on at least one of said first or second surfaces of said core, said uncured prepreg having an outer surface and an inner surface, said inner surface being adjacent to said core first or second surface and said uncured prepreg comprising a thermosetting resin that has a cure temperature; and

an uncured pigmented layer attached directly to the outer surface of said uncured prepreg, said uncured pigmented layer comprising:

an uncured pigmented binder resin, said uncured pigmented binder resin comprising an uncured thermoplastic resin and a pigment wherein said thermoplastic resin has a cure temperature that is equal to or less than the cure temperature of said uncured thermosetting resin present in said prepreg; and

~~————— a substrate on which said pigmented binder resin is located, said substrate having a melting point that is above the cure temperature of said prepreg.~~

12. (original): An uncured panel assembly according to claim **11** wherein said core comprises honeycomb.

13. (currently amended): An uncured panel assembly according to claim ~~10~~ **11** wherein said uncured thermoplastic resin present in said uncured pigmented binder is polyvinyl butyral.

14. (currently amended): An uncured panel assembly according to claim ~~10~~ **11** wherein said uncured thermosetting resin present in said uncured prepreg is selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy.

15. (currently amended): An uncured panel assembly according to claim ~~10~~ **11** ~~in which further comprises a substrate on which said pigmented binder resin is located, said substrate having a melting point that is above the cure temperature of said prepreg said substrate comprises a textile substrate and/or a thermoplastic film substrate.~~

16. (currently amended): An uncured panel assembly according to claim **15** wherein said ~~thermoplastic film substrate comprises a textile substrate and/or a film substrate is a film comprising polyethylene terephthalate.~~

17. (currently amended): An uncured panel assembly according to claim **16** wherein said film substrate comprises ~~comprising~~ polyethylene terephthalate ~~is between about 36 and 50 microns thick.~~

18. (original): An uncured panel assembly according to claim **15** wherein said textile substrate comprises a textile selected from the group consisting of glass fabric and polyester matt.

19. (currently amended): An uncured panel assembly according to claim ~~10~~ **11** wherein said pigment comprises titanium dioxide.

20. (original): An uncured panel assembly according to claim **19** wherein said uncured thermoplastic resin present in said uncured pigmented binder comprises polyvinyl butyral, said uncured thermosetting resin present in said prepreg is selected from the group consisting of phenolic

resole, phenolic novalac and flame retardant epoxy and said substrate comprises a thermoplastic film substrate comprising polyethylene terephthalate.

21. (currently amended): A panel assembly comprising an uncured panel assembly according to claim ~~10~~ 11 that has been heated to a processing temperature that is equal to or above the cure temperature for said thermosetting resin for a sufficient time to cure both said thermosetting resin in said prepreg and said thermoplastic resin present in said pigmented binder, ~~said processing temperature being below the melting point of said substrate and wherein said thermoplastic film substrate, if any, has been removed from said panel assembly.~~

22. (original): A method for making an uncured pigmented panel assembly, said method comprising the steps of:

providing a core having a first and a second surface, said first and second surfaces being located on opposite sides of said core and defining the thickness of said core;

locating at least one uncured prepreg on at least one of said first or second surfaces of said core, said uncured prepreg having an outer surface and an inner surface, said inner surface being located adjacent to said core first or second surface and said uncured prepreg comprising a thermosetting resin that has a cure temperature; and

applying an uncured pigmented layer directly to the outer surface of said uncured prepreg, said uncured pigmented layer comprising an uncured pigmented binder resin, said uncured pigmented binder resin comprising an uncured thermoplastic resin and a pigment wherein said thermoplastic resin has a cure temperature that is equal to or less than the cure temperature of said uncured thermosetting resin present in said prepreg.

23. (currently amended): A method for making an uncured pigmented panel assembly according to claim ~~21~~ 22 wherein said uncured pigmented layer comprises a substrate on which said pigmented binder resin is located, said substrate having a melting point that is above the cure temperature of said prepreg.

24. (original): A method for making an uncured pigmented panel assembly according to claim 22 wherein said core comprises honeycomb.

25. (original): A method for making an uncured pigmented panel assembly according to claim **22** wherein said uncured thermoplastic resin present in said uncured pigmented binder is polyvinyl butyral.

26. (original): A method for making an uncured pigmented panel assembly according to claim **22** wherein said uncured thermosetting resin present in said uncured prepreg is selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy.

27. (original): A method for making an uncured panel assembly according to claim **23** in which said substrate comprises a textile substrate and/or a thermoplastic film substrate.

28. (original): A method for making an uncured panel assembly according to claim **27** wherein said substrate comprises a thermoplastic film substrate comprising polyethylene terephthalate.

29. (original): A method for making an uncured panel assembly according to claim **28** wherein said film comprising polyethylene terephthalate is between about 36 and 50 microns thick.

30. (currently amended): A method for making an uncured panel assembly according to claim ~~**21**~~ **22** wherein said pigment comprises titanium dioxide.

31. (currently amended): A method for making an uncured panel assembly according to claim ~~**23**~~ **27** wherein said pigment comprises titanium dioxide, said uncured thermoplastic resin present in said uncured pigmented binder comprises polyvinyl butyral, said uncured thermosetting resin present in said prepreg is selected from the group consisting of phenolic resole, phenolic novalac and flame retardant epoxy and said substrate comprises a thermoplastic film substrate comprising polyethylene terephthalate.

32. (original): A method according to claim **22** that includes the additional steps of heating said uncured panel assembly to a processing temperature that is equal to or above the cure temperature for said thermosetting resin for a sufficient time to cure both said thermosetting resin in said prepreg and said thermoplastic resin present in said pigmented binder to form a cured panel assembly.

33. (currently amended): A method according to claim **23** that includes the additional step of heating said uncured panel assembly to a processing temperature that is equal to or above the cure temperature for said thermosetting resin for a sufficient time to cure both said thermosetting resin in said prepreg and said thermoplastic resin present in said pigmented binder to form a cured panel assembly, wherein said processing temperature is below the melting point of said substrate ~~and said thermoplastic film substrate, if any, is removed from said cured panel assembly.~~